Product/Process Change Notification

N° 2023-252-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Change of mold compound affecting products in package family TO220 and TO247

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2024-04-11.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46“, which stipulates:
  “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”

  Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board Dr. Herbert Diess
Management Board Jochen Hanebeck (CEO), Elke Reichart, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg
Registered office Neubiberg Commercial register Amtsgericht München HRB 126492

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Products affected

Please refer to attached affected product list PCN_2023-252-A_[customer-no].pdf

Detailed change information

Subject: Change of mold compound affecting products in package family TO220 and TO247

Reason/Motivation: Infineon is ensuring business continuity and supply by moving on to ecologically aware and green mold compound

Description	Old	New
PROCESS - ASSEMBLY: Change of mold compound / encapsulation material	TIJ: Epoxy Resin A (TO220 & TO247) GTBF: Epoxy Resin A (TO247) TFME: Epoxy Resin C (TO220)	TIJ: Epoxy Resin B (TO220 & TO247) GTBF: Epoxy Resin B (TO247) TFME: Epoxy Resin D (TO220)
PROCESS - ASSEMBLY: Change of direct material supplier	TIJ: Supplier X (TO220 & TO247) GTBF: Supplier X (TO247) TFME: Supplier Z (TO220)	TIJ: Supplier Y (TO220 & TO247) GTBF: Supplier Y (TO247) TFME: Supplier Y(TO220)

Product identification

Traceability assured via date code.
SP number and ordering part number are different

Anticipated impact of change

Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No change in fit and form.

DeQuMa-ID(s): SEM-PA-11 / SEM-PA-16

Attachments

PCN_2023-252-A_[customer-no].pdf	affected product list
2_cip23252_A	qualification report, available upon request
3_cip23252_A	customer information package, available upon request

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Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2024-08-29
Last order date (LOD) [2]	2024-08-29
Last delivery date (LDD) [3]	2025-02-28

[1] Provided date or earlier after customer approval.
[2] Last date where orders for unchanged products will be accepted.
[3] Last date for delivery of unchanged products. Delivery of changed products can be earlier (see Intended start of delivery) and depends on approval.

If you have any questions, please do not hesitate to contact your local sales office.

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Change of mold compound affecting products in package family TO220 and TO247

Affected products sold to DIGI-KEY, THIEF RIVER FALLS, USA (4002348)

Sales name	SP number	OPN	Package	Customer part number
AUIRF540Z	SP001516500	AUIRF540Z	PG-TO220-3-904	AUIRF540Z
AUIRFB8405	SP001516720	AUIRFB8405	PG-TO220-3-904	AUIRFB8405
AUIRFB8407	SP001517430	AUIRFB8407	PG-TO220-3-904	AUIRFB8407
AUIRFB8409	SP001521544	AUIRFB8409	PG-TO220-3-904	AUIRFB8409
AUIRG4PH50S	SP001512028	AUIRG4PH50S	PG-TO247-3-901	AUIRG4PH50S